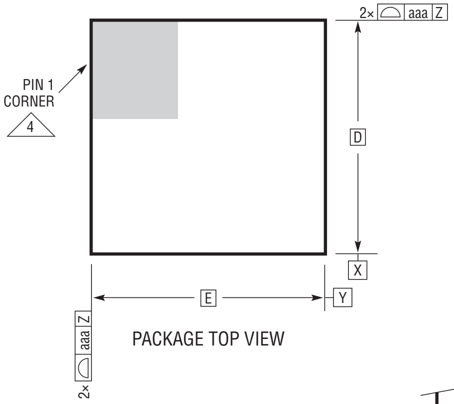
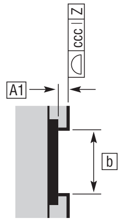
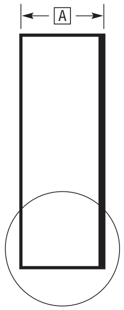
LGA Package
25-Lead (4mm × 4mm × 1.25mm)
(Reference LTC DWG# 05-08-7013 Rev Ø)



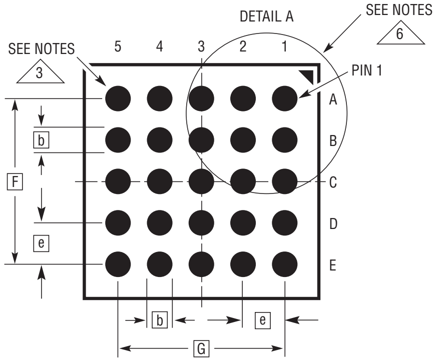
PACKAGE TOP VIEW



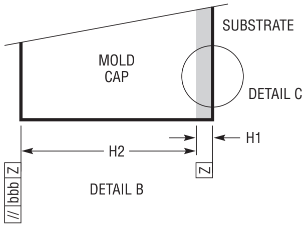
DETAIL C

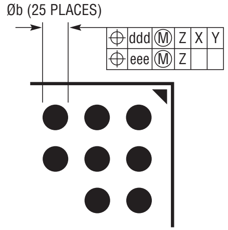


DETAIL B
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW





DETAIL A

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

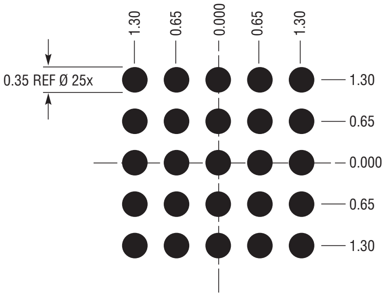
2. ALL DIMENSIONS ARE IN MILLIMETERS

3. LAND DESIGNATION PER JEP95

4. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL,
BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR
MARKED FEATURE

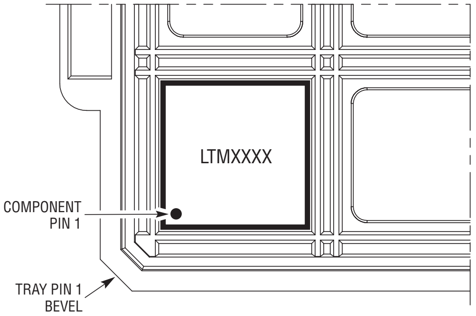
5. PRIMARY DATUM -Z- IS SEATING PLANE

6. ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY
AMONG µModule PRODUCTS. REVIEW EACH PACKAGE
LAYOUT CAREFULLY



SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	**MIN**	**NOM**	**MAX**	**NOTES**
A	1.15	1.25	1.35	
A1			0.03	
b	0.32	0.35	0.38	PAD DIMENSION
D		4.00		
E		4.00		
e		0.65		
F		2.60		
G		2.60		
H1		0.25 REF		SUBSTRATE THK
H2		1.00 REF		MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.10	
ddd			0.15	
eee			0.08	



PACKAGE IN TRAY LOADING ORIENTATION

LGA 25 0819 REV Ø